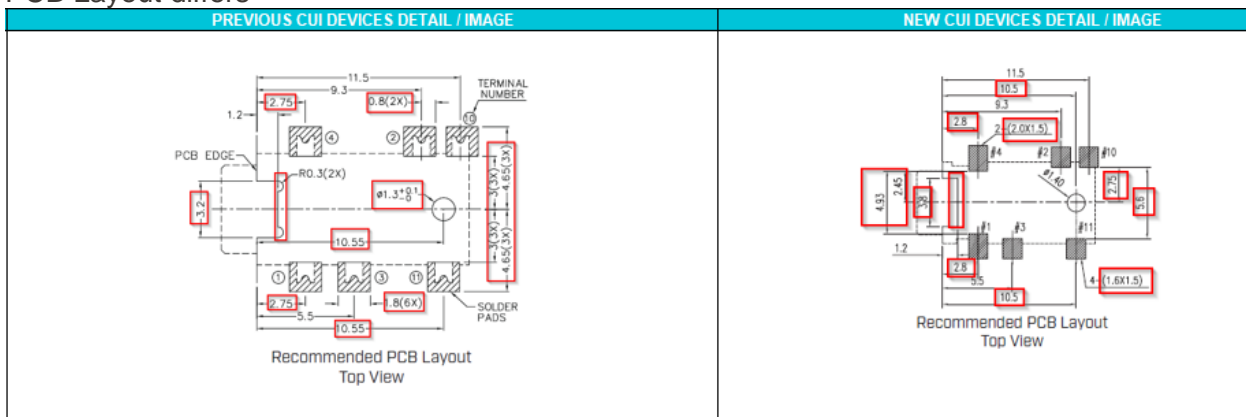


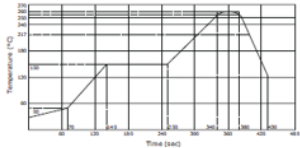
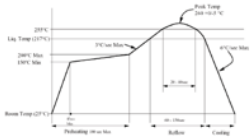
2. PCB Layout differs



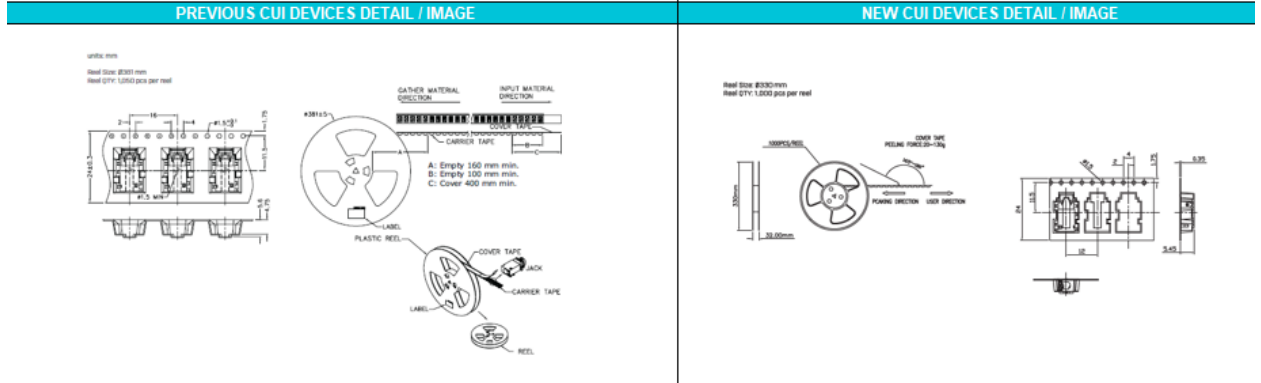
3. Housing material differs

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4. Reflow Soldering Difference

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5. Tape and reel packaging differs



Affected Date Code: **11/15/2022**

Product Availability: **Channel availability mid Q4**

Additional Information:

PCN Approval:

Operations/Quality



Product Management



Nick Wolfe

11/21/2022